

IN THE CLAIMS

Please amend the claims as shown in the following listing of claims.

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b<sup>1</sup>

1. (Currently Amended) An epoxy resin composition for encapsulating of semiconductors which is used for so-called area mounting type semiconductor devices formed by mounting semiconductor elements on one side of a printed circuit board or a metallic lead frame and encapsulating with a resin substantially only the side on which the semiconductor elements are mounted, and which comprises (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, characterized in that properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions,  $a \geq 10^R$  ( $R=10 \times (b+c)-1$ ,  $300 \leq a \leq 20000$  and  $0.15 \leq b+c \leq 0.50$  in which a denotes a flexural modulus ( $N/mm^2$ ) at molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature.

2. (Original) An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the cured product has a moisture absorption rate of not more than 0.20% by weight after treated for 168 hours in an environment of 85°C and 60% in relative humidity.

3. (Previously Amended) An epoxy resin composition for encapsulating of semiconductors according to claim 1 wherein the epoxy resin and/or the phenolic resin have/has a naphthalene skeleton.

4. (Previously Amended) A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 1.

5. (Previously Added) An epoxy resin composition for encapsulating of semiconductors according to claim 2 wherein the epoxy resin and/or the phenolic resin have/has a naphthalene skeleton.

B<sup>1</sup>  
6. (Previously Added) A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 2.

7. (Previously Added) A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 3.

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8. (New) An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the epoxy resin (A) comprises a biphenyl type epoxy resin, and the phenolic resin (B) comprises a phenolic aralkyl resin and/or naphthol aralkyl resin.

9. (New) An epoxy resin composition for encapsulating of semiconductors according to claim 2, wherein the epoxy resin (A) comprises a biphenyl type epoxy resin, and the phenolic resin (B) comprises a phenolic aralkyl resin and/or naphthol aralkyl resin.

10. (New) An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the epoxy resin (A) comprises an epoxy resin having a naphthalene backbone, and the phenolic resin (B) comprises a naphthol aralkyl resin.

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11. (New) An epoxy resin composition for encapsulating of semiconductors according to claim 2, wherein the epoxy resin (A) comprises an epoxy resin having a naphthalene backbone, and the phenolic resin (B) comprises a naphthol aralkyl resin.

12. (New) A method for encapsulating a semiconductor comprising mounting a semiconductor element on one side only of a printed circuit board or a metallic lead frame and encapsulating with an epoxy resin composition substantially only on the side of the printed circuit board on which the semiconductor element is mounted, said epoxy resin composition comprising (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, characterized in that properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions,  $a \geq 10^R$  ( $R=10 \times (b+c)-1$ ,  $300 \leq a \leq 20000$  and  $0.15 \leq b+c \leq 0.50$  in which  $a$  denotes a flexural modulus ( $N/mm^2$ ) at

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molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature.

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